

➤ **Features**

- Size 0.18*0.12 inch /4.5*3.2 mm
- RoHS compliant, lead-free and halogen-free
- Fast response to fault current
- Low resistance
- Low profile
- Compatible with high temperature solders

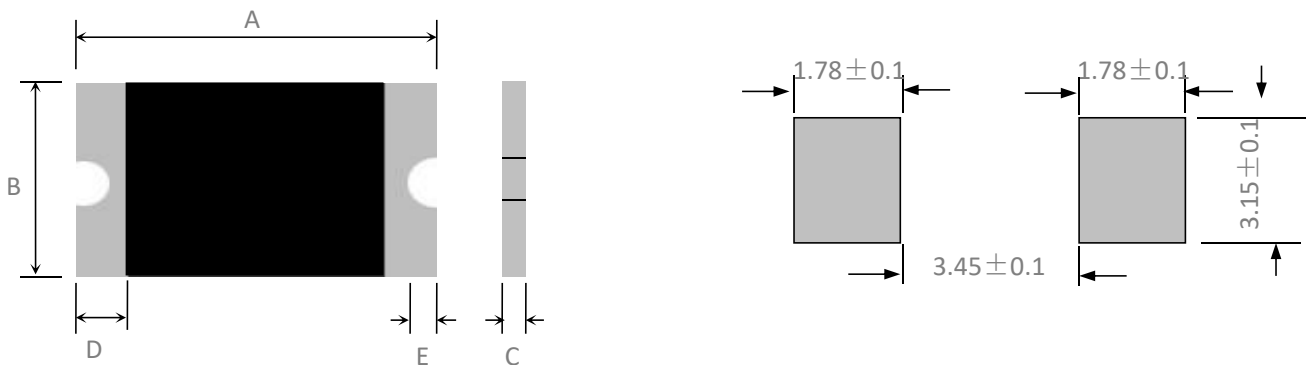
➤ **Applications**

- Computer, Mobile phones, Multimedia
- Automotive, Industrial controls, Telephony and broadband
- Game machines, Portable electronics, Battery

➤ **Electrical Characteristics (25°C)**

Part Number	I_{hold}	I_{trip}	V_{max}	I_{max}	$P_{d\ typ}$	Time to trip		R_{min}	R_{1max}
	(A)	(A)	(V _{dc})	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)
BSMD1812L-600-12V	6.00	12.0	12	50	2.0	20.00	5.00	0.0008	0.010

➤ **Physical Dimensions & Recommended Pad Layout (mm)**



Part Number	Marking	Quantity	A		B		C		D	E
			Min	Max	Min	Max	Min	Max	Min	Min
BSMD1812L-600-12V		1500	4.37	4.73	3.07	3.41	0.50	1.10	0.30	0.25

➤ Vocabulary

- I_{hold}** = Hold current: maximum current device will pass without tripping in 25°C still air.
- I_{trip}** = Trip current: minimum current at which the device will trip in 25°C still air.
- V_{max}** = Maximum voltage device can withstand without damage at rated current (**I_{max}**).
- I_{max}** = Maximum fault current device can withstand without damage at rated voltage (**V_{max}**).
- P_{d typ.}** = Typical power dissipated from device when in the tripped state at 25°C still air.
- R_{min}** = Minimum resistance of device in initial (un-soldered) state.
- R_{1max}** = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

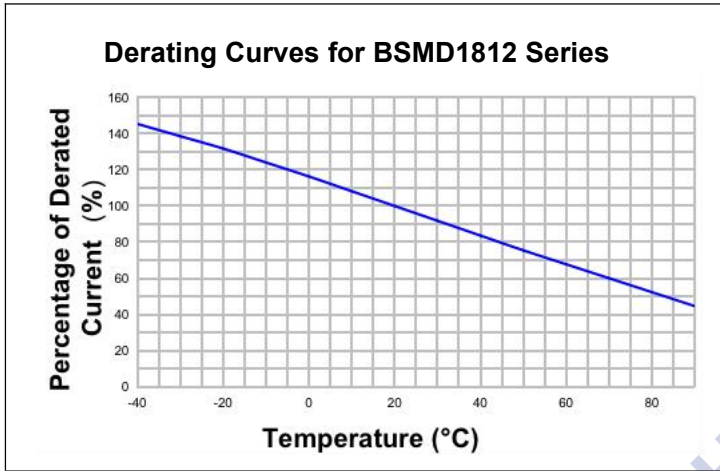
Caution: Operation beyond the specified ratings may result in damage and possible arcing and flame.



➤ Warning

- Users shall independently assess the suitability of these devices for each of their applications.
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire.
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration.
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the prolonged of these PPTC devices.
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses.
- Circuits with inductance may generate a voltage ($L di/dt$) above the rated voltage of the PPTC device.

➤ **Thermal Derating Curve**



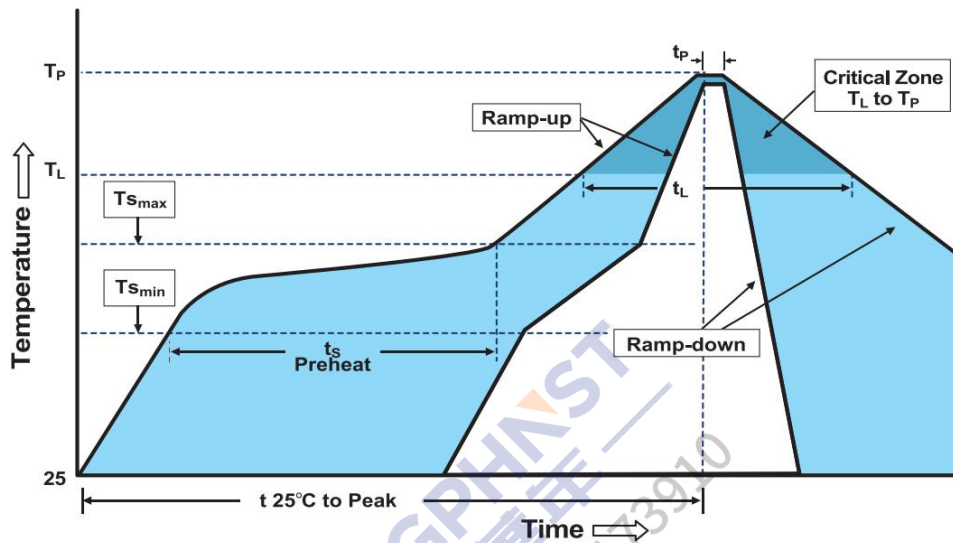
➤ **Thermal Derating Chart**

Part Number	Ambient operating temperature hold current(I_{hold})								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
BSMD1812L-600-12V	9.0	8.0	7.0	6.0	5.2	4.6	4.2	3.7	3.1

➤ **Environmental Specifications**

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hours	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

➤ **Soldering Parameters**



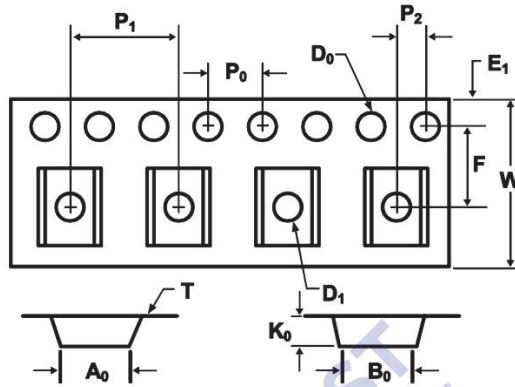
Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate($T_{s_{max}}$ to T_p)	3°C/second max
Preheat -Temperature Min($T_{s_{min}}$) -Temperature Max($T_{s_{max}}$) -Time($T_{s_{min}}$ to $T_{s_{max}}$)	150°C 200°C 60~180 seconds
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~150 seconds
Peak Temperature(T_p)	260°C
Ramp-Down Rate	6°C/second max
Time 25°C to Peak Temperature	8 minutes max
Storage Condition	0°C~30°C, 30%-60%RH

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead-free.
- Recommended maximum paste thickness is 0.25mm.
- Devices can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

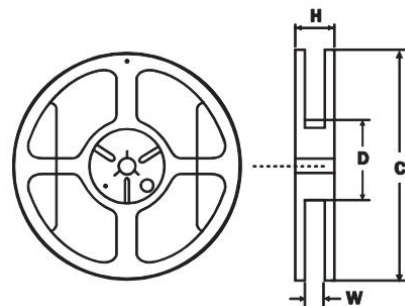
Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

➤ **Tape And Reel Specifications (mm)**



Governing Specifications	BSMD1812-600-12V
W	12.0 ± 0.3
F	5.5 ± 0.05
E ₁	1.75 ± 0.1
D ₀	1.55 ± 0.05
D ₁	1.55 _{min}
P ₀	4.0 ± 0.1
P ₁	8.0 ± 0.1
P ₂	2.0 ± 0.05
A ₀	3.58 ± 0.1
B ₀	4.93 ± 0.1
T	0.2 ± 0.1
K ₀	1.25 ± 0.1
Leader _{min}	390
Trailer _{min}	160

Reel Dimensions	
C	φ178 ± 1.0
D	φ60.2 ± 0.5
H	16.0 ± 0.5
W	13.2 ± 1.5



➤ **Contact information**

SHENZHEN BHFUSE INDUSTRIAL CO., LTD

TEL: 0755-85259917

E-MAIL: sales@bhfuse.com